

Smart Structures and Integrated Systems (ss08)

Part of SPIE's 10th Annual International Symposium on
Smart Structures and Materials
2–6 March 2003 • Town & Country Resort and Convention Center • San Diego, CA USA

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This conference focuses on topics related to analysis, design, testing, and failure resolution of smart structures systems. The emphasis is on the interplay of actuation, sensing, and processing capabilities to create active systems with new functional capabilities. The goal is to create a multidisciplinary forum to bring together developments in diverse application areas in

aeronautical, space and civil applications. The scope of the conference ranges from system level evaluation of smart structures to development and modeling of new actuation and sensing techniques for adaptive structures. Papers are encouraged that describe developments in active materials, "smart" structural components, and integration of these and other constituent technologies into advanced systems that hold the potential for expanding the application of smart structures and integrated systems.

Topics include:

- applications of smart structures technology to:
- rotorcraft
- aircraft systems
- space systems
- civil systems
- automotive systems
- flexible robotic systems
- adaptive optics
- active vibration control
- active shape control
- active noise suppression
- active damping control
- structural health monitoring
- damage detection and mitigation
- damage and remaining life assessment
- actuator and sensor technologies
- embedded sensors and actuators in structures
- integration of active materials into controlled systems
- microelectromechanical sensors and actuators
- micropositioning devices
- solid state motors
- modeling, analysis, and design techniques
- modeling and mechanics of structural sensing and actuation
- modeling, simulation, and design of controlled systems
- multidisciplinary design optimization
- structural integrity and interfaces placement of actuators and sensors.

Abstract Due Date: 31 July 2002
Manuscript Due Date: 3 February 2003

Submission of Abstracts for Smart Structures and Materials symposium

Abstract Due Date: 31 July 2002

Manuscript Due Date: 3 February 2003

Submissions imply the intent of at least one author to register, attend the symposium, and present the paper (either orally or in poster format), and submit a full-length manuscript.

Your abstract must include all of the following:

1. **SUBMIT TO:** SS08, BAZ
2. **SUBMIT EACH ABSTRACT TO ONE CONFERENCE ONLY** Smart Structures and Integrated Systems (ss08)
3. **ABSTRACT TITLE**
4. **AUTHOR LISTING** (principal author first)
For each author: First (given) name (initials not acceptable), Last (family) name, Affiliation, Mailing address, Telephone, Fax, and Email address.
5. **PRESENTATION**
Indicate your preference for "Oral Presentation" or "Poster Presentation." Final placement is subject to chairs' discretion.
6. **BRIEF BIOGRAPHY** (principal/presenting author)
Approximately 50 words.
7. **ABSTRACT TEXT**
Approximately 250 words.
8. **KEYWORDS**
List a maximum of five keywords.

Conditions of Acceptance

- **Authors are expected to secure registration fees and travel and accommodation funding, independent of SPIE, through their sponsoring organizations before submitting abstracts.**
- Only original material should be submitted.
- Commercial papers, descriptions of papers with no research/development content, and papers where supporting data or a technical description cannot be given for proprietary reasons will not be accepted for presentation in this symposium.
- Abstracts should contain enough detail to clearly convey the approach and the results of the research.
- Government and company clearance to present and publish should be final at the time of submittal. Authors are required to warrant to SPIE in advance of publication of the Proceedings that all necessary permissions and clearances have been obtained, and that submitting authors are authorized to transfer copyright of the paper to SPIE .
- Applicants will be notified of acceptance by mail no later than 9 December 2002. Early notification of acceptance will be placed on the SPIE Web site the week of 25 November 2002 at www.spie.org/info/ss-nde/

Paper Review

To ensure a high-quality conference, all abstracts and Proceedings of SPIE manuscripts will be reviewed by the Conference Chair/Editor for technical merit and suitability of content. Conference Chair/Editors may require manuscript revision before approving publication, and reserve the right to reject for presentation or publication any paper that does not meet content or presentation expectations. SPIE's decision on whether to publish manuscripts is final.

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All authors are **STRONGLY ENCOURAGED** to submit their abstracts by the due date using the "submit an abstract" link on the Web at:

[www.spie.org/info/\[sympinitial\]](http://www.spie.org/info/[sympinitial])

Using this method of submission ensures that your abstract will be immediately accessible to the conference chair for review. Using other methods of submission (listed below) will delay the processing of your abstract.

- or E-MAIL each abstract separately to: abstracts@spie.org in ASCII text (not encoded) format. IMPORTANT: to ensure receipt and proper processing of your abstract, the Subject line must include only the following:
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Abstracts submitted via the Web at [www.spie.org/info/\[ss-nde/](http://www.spie.org/info/[ss-nde/) (250 words) and accepted by the conference chair(s) for presentation at the meeting will be printed in an Abstract Book distributed to attendees of the symposium.

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Proceedings of SPIE

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